



1. Four layer PCB, material FR-4, copper 1 oz, overall thickness 1.6 mm.

2. Layers structure:

- Front copper
- Prepreg 0.25 mm
- Internal copper layer 1
- Core 1 mm
- Internal copper layer 2
- Prepreg 0.25 mm
- Bottom copper

3. Green solder mask on both sides.

4. White silkscreen on top layer.

5. Finish: HASL.

=AK =

Sheet:

File: SoilSensor.kicad\_pcb

Title: Soil Moisture Sensor

Size: A4

Date: 2020-02-26

KiCad E.D.A. kicad (5.1.4) - 1

Rev: 2.0

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